

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	526700	(trace conductor wire redistribut\$5) same (connect\$4 interconnect\$4) same (bond bonding terminal electrode pad paddle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/18 17:37
L2	2781657	(semiconductor die dice chip ic electronic component (integrated adj circuit)) with (first second top bottom upper lower first second plurality plural multi multiple) sand 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/18 17:38
L3	69102	(semiconductor die dice chip ic electronic component (integrated adj circuit)) with (first second top bottom upper lower first second plurality plural multi multiple) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/18 17:39
L4	64815	(terminal contact electrode pad) same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/18 17:40
L5	28183	(stack\$4 mount\$4 level) same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/18 17:40
L6	1166	(offset\$4 cascad\$3 slant\$3 tilt\$3) same 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/18 17:42